

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	("6335208").PN.	USPAT; USOCR	OR	OFF	2006/07/09 16:27
L2	1	("20020173070").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/09 16:36
L3	408	(@ad<"20000816") and loc and (chip or die) and ("ic" or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 18:05
L4	112	L3 and (encapsulant or encapsulate or encapsulation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 16:37
L5	186	("5677566").URPN.	USPAT	OR	OFF	2006/07/09 17:00
L6	58	L5 and (@ad<"20000816")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 17:00
L7	89	(@ad<"20000816") and ((lead adj under) or luc) and (chip or die) and ("ic" or semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 17:59
L8	88	L7 not L6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 17:59
L9	61	L8 not micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 17:59
L10	4	("6534861").URPN.	USPAT	OR	OFF	2006/07/09 18:02

EAST Search History

L11	493	(@ad<"20000816") and 257/778. ccls. and (encapsulate or encapsulation or epoxy) and wire\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 18:06
L12	497	(@ad<"20000816") and 257/778. ccls. and (encapsulate or encapsulation or epoxy) and wire\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 18:06
L13	85	L12 and ((wire\$1 and (board or substrate or pwb or pcb or tape or polyimide)) with (hole or opening or cavity or aperture or recess))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 18:42
L14	72	"6218731"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/09 18:42